

N-Ch 100V Fast Switching MOSFETs

❖ GENERAL DESCRIPTION

The AM6008 is the high cell density trench N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the Synchronous Rectification for AC/DC Quick Charger.

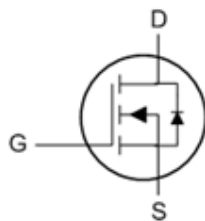
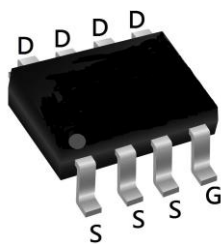
❖ FEATURES

- 100% EAS Guaranteed
- Low $R_{DS(ON)}$
- Low Gate Charge
- RoHs and Halogen-Free Compliant

❖ Product Summary

BVDSS	RDSON	ID
100V	8mΩ	13.5A

SOP8 Pin Configuration



❖ ORDER/MARKING INFORMATION

Order Information	Top Marking
<p>AM6008 X X</p> <p>Package Type Packing</p> <p>S: SOP-8L Blank : Tube</p> <p> A : Taping</p>	<p>Logo← AM6 0 0 8 → Part number</p> <p> YY WW X → ID code: internal</p> <p> WW: 01~52</p> <p> Year: 10=2010</p> <p> 11=2011</p> <p> ⋮</p> <p> 19=2019</p>

❖ Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ C$	Continuous Drain Current ¹	13.5	A
$I_D@T_A=70^\circ C$	Continuous Drain Current ¹	10.5	A
I_{DM}	Pulsed Drain Current ²	55	A
EAS	Single Pulse Avalanche Energy ³	33	mJ
I_{AS}	Avalanche Current	15	A
$P_D@T_A=25^\circ C$	Total Power Dissipation ⁴	3.1	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

❖ Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	---	40	$^\circ C/W$
	Thermal Resistance Junction-Ambient ¹	---	75	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	24	$^\circ C/W$

❖ Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =13.5A	---	6.6	8	mΩ
	Static Drain-Source On-Resistance ²	V _{GS} =4.5V, I _D =11.5A	---	8.7	10.5	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	---	2.3	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =80V, V _{GS} =0V, T _J =55°C	---	---	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =13.5A	---	75	---	S
Q _g	Total Gate Charge (10V)	V _{DS} =50V, V _{GS} =10V, I _D =13.5A	---	45	---	nC
Q _g	Total Gate Charge (4.5V)		---	19.3	---	
Q _{gs}	Gate-Source Charge		---	9.5	---	
Q _{gd}	Gate-Drain Charge		---	4.8	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =50V, V _{GS} =10V, R _G =3Ω, I _D =13.5A	---	10	---	ns
T _r	Rise Time		---	6.5	---	
T _{d(off)}	Turn-Off Delay Time		---	45	---	
T _f	Fall Time		---	7.5	---	
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, f=1MHz	---	3320	---	pF
C _{oss}	Output Capacitance		---	605	---	
C _{rss}	Reverse Transfer Capacitance		---	20	---	

❖ Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	5	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.1	V
t _{rr}	Reverse Recovery Time	I _F =13.5A, di/dt=100A/μs,	---	33	---	nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C	---	150	---	nC

Note :

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.3mH, I_{AS}=15A
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

❖ Typical Characteristics

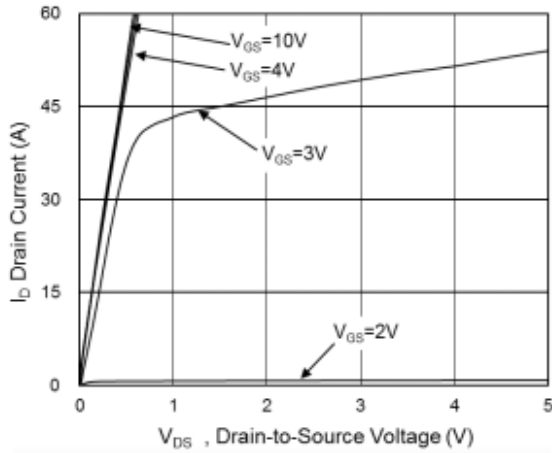


Fig.1 Typical Output Characteristics

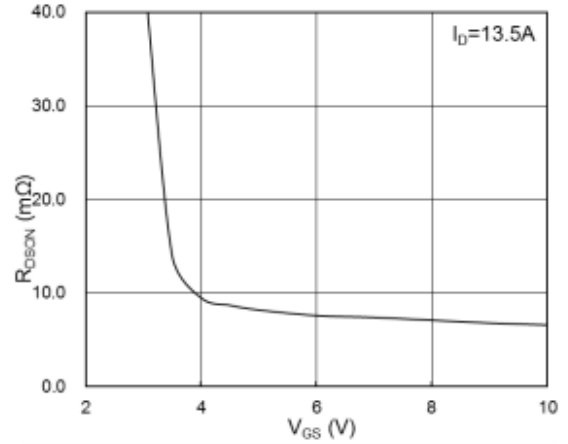


Fig.2 On-Resistance vs. G-S Voltage

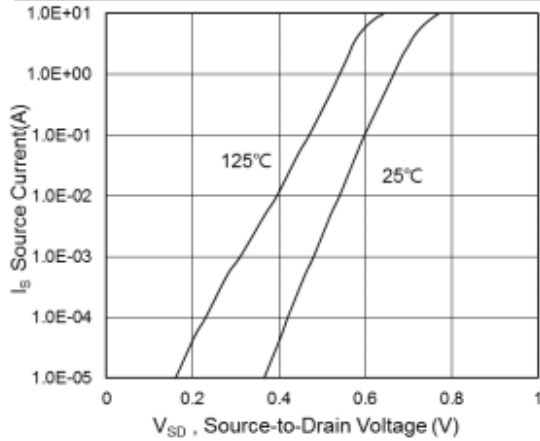


Fig.3 Source-Drain Forward Characteristics

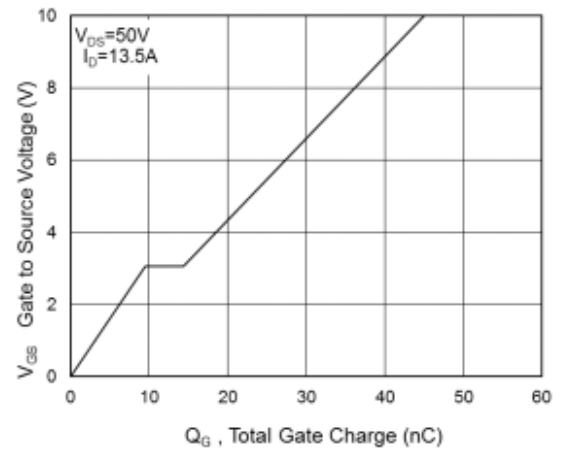


Fig.4 Gate-Charge Characteristics

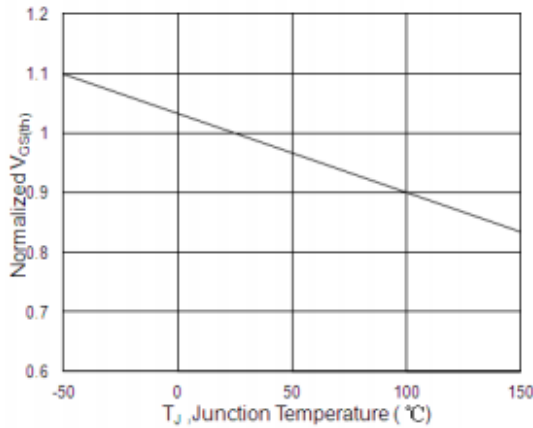


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

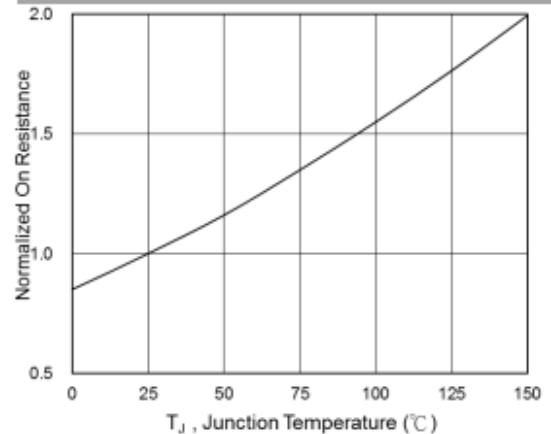


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

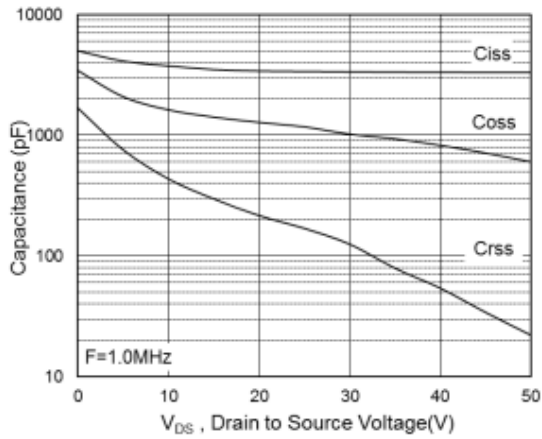


Fig.7 Capacitance

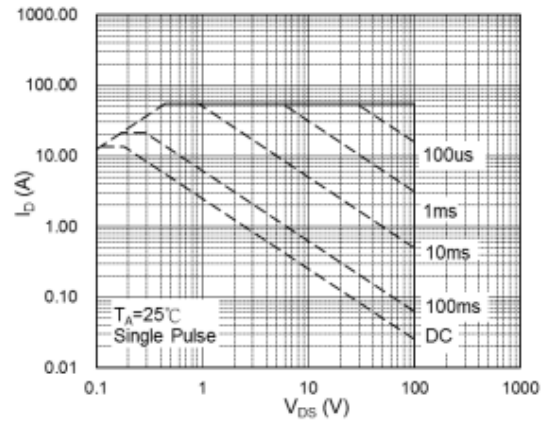


Fig.8 Safe Operating Area

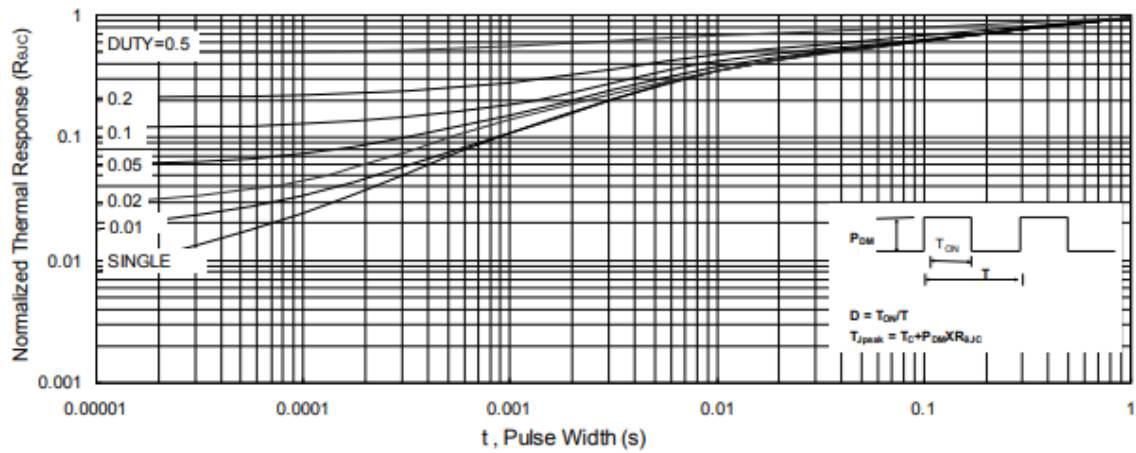


Fig.9 Normalized Maximum Transient Thermal Impedance

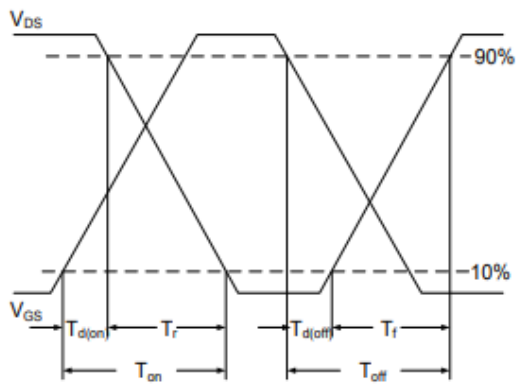


Fig.10 Switching Time Waveform

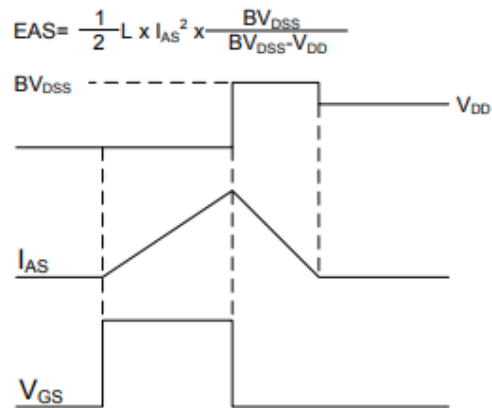
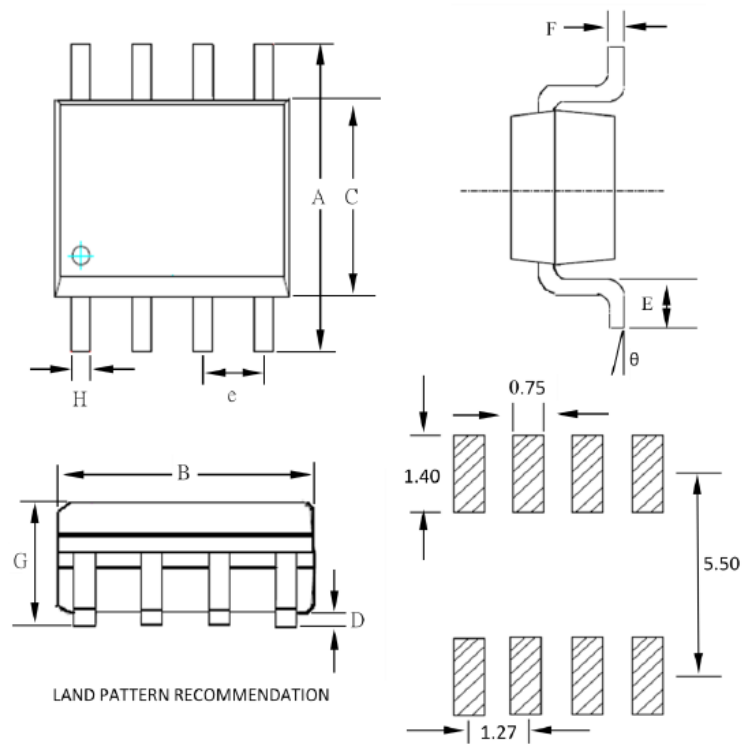


Fig.11 Unclamped Inductive Switching Waveform

❖ PACKAGE OUTLINES

SOP8 Package Outline



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	5.75	6.00	6.25	0.226	0.236	0.246
B	4.70	4.90	5.15	0.185	0.193	0.203
C	3.70	3.90	4.10	0.146	0.154	0.161
D	0.05	--	0.25	0.002	--	0.010
E	0.40	--	1.27	0.016	--	0.050
F	0.16	--	0.25	0.006	--	0.010
G	1.23	--	1.75	0.048	--	0.069
e	1.07	1.27	1.47	0.042	0.050	0.058
H	0.31	--	0.51	0.012	--	0.020
θ	0°	--	8°	0°	--	8°